VS-HFA16TA60CS-M3

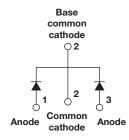
Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 2 x 8 A



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D²PAK (TO-263AB)



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 8 A					
V _R	600 V					
V _F at I _F	1.4 V					
t _{rr} typ.	18 ns					
T _J max.	150 °C					
Package	D ² PAK (TO-263AB)					
Circuit configuration	Common cathode					

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA16TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{BBM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage	V _R		600	V			
Maximum continuous forward current	- I _F	T _C = 100 °C	8				
per device			16	А			
Single pulse forward current	I _{FSM}		60	A			
Maximum repetitive forward current	I _{FRM}		24				
Maximum power dissipation	P _D	T _C = 25 °C	36	W			
		T _C = 100 °C	14	v			
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C			

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COMPLIANT



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ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25$ °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		600	-	-		
Maximum forward voltage	V _{FM}	I _F = 8.0 A		-	1.4	1.7	V	
		I _F = 16 A	See fig. 1	-	1.7	2.1		
		I _F = 8.0 A, T _J = 125 °C		-	1.4	1.7		
Maximum reverse leakage current	I _{RM}	$V_{R} = V_{R}$ rated	See fig. 0	-	0.3	5.0		
Maximum reverse leakage current		T_J = 125 °C, V_R = 0.8 x V_R rated	See fig. 2	-	100	500	μA	
Junction capacitance	CT	V _R = 200 V See fig. 3		-	10	25	pF	
Series inductance	L _S	Measured lead to lead 5 mm from pa	ackage body	-	8.0	-	nH	

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ($T_J = 25$ °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
	t _{rr}	I _F = 1.0 A, dI _F /dt = 200	A/μs, V _R = 30 V	-	18	-		
Reverse recovery time See fig. 5, 6 and 16	t _{rr1}	T _J = 25 °C		-	37	55	ns	
	t _{rr2}	T _J = 125 °C		-	55	90		
Peak recovery current	I _{RRM1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/μs V _B = 200 V	-	3.5	5.0	Α	
See fig. 7 and 8	I _{RRM2}	T _J = 125 °C		-	4.5	8.0	A	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	65	138	nC	
See fig. 9 and 10	Q _{rr2}	T _J = 125 °C		-	124	360	nc	
Peak rate of fall of recovery current	dl _{(rec)M} /dt1	T _J = 25 °C	-	-	240	-	A/up	
during t_b , see fig. 11 & 12	dl _{(rec)M} /dt2	T _J = 125 °C		-	210	-	A/µs	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	IETER SYMBOL TEST CONDITIONS				MAX.	UNITS	
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conducting			-	-	3.5		
Junction to case, both legs conducting			-	-	1.75	к/w	
Thermal resistance, junction to ambient	R _{thJA}	JA Typical socket mount		-	80	-	
Weight			-	2	-	g	
Weight			-	0.07	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style D ² PAK (TO-263AB)		HFA16	TA60CS		



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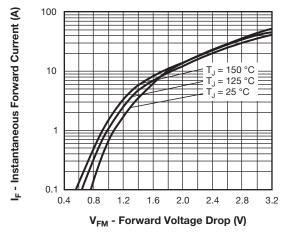


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

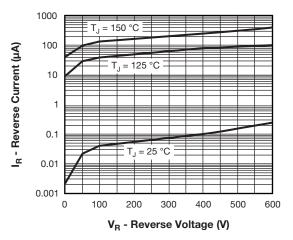


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

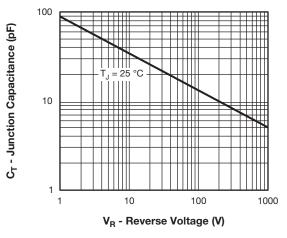


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

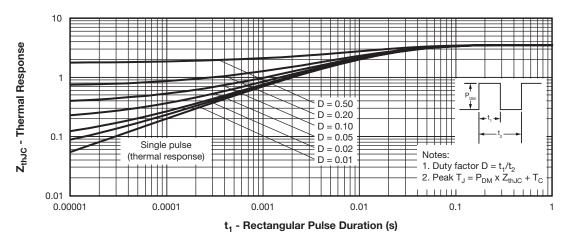


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

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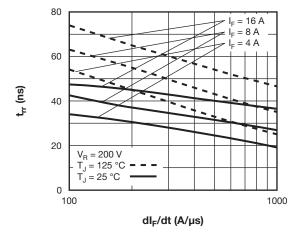


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

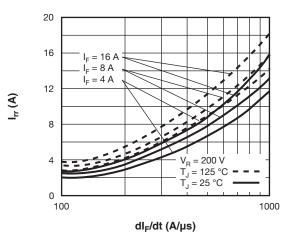
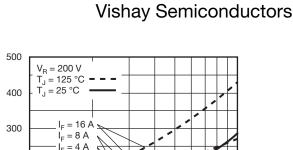


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)



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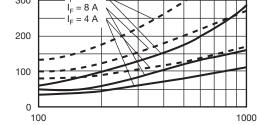




Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

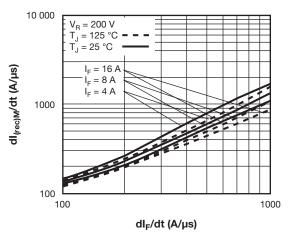
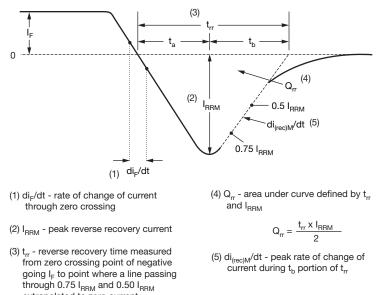


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt (Per Leg)



Q_{rr} (nC)

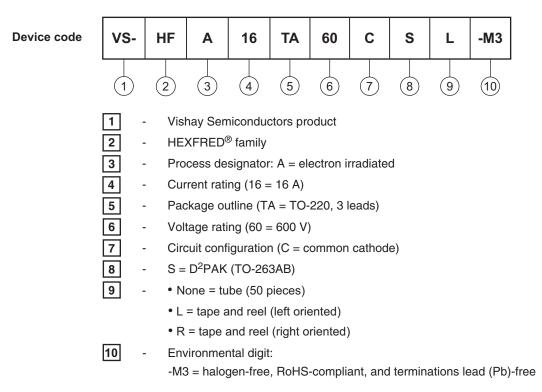
	extrapolated to zero current.	
	Fig. 9 - Reverse Recovery Waveform and Definitions	
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ORDERING INFORMATION TABLE

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ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-HFA16TA60CS-M3	50	1000	Antistatic plastic tube					
VS-HFA16TA60CSR-M3	800	800	13" diameter reel					
VS-HFA16TA60CSL-M3	800	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96164				
Part marking information	www.vishay.com/doc?95444				
Packaging information	www.vishay.com/doc?96424				
SPICE model	www.vishay.com/doc?96596				

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D²PAK

DIMENSIONS in millimeters and inches



ota	ted	90	°C
<u>S</u>	cale	<u>ə:</u> 8	:1

SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	0.00	0.254	0.000	0.010		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
с	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	

SYMBOL	MILLIM	MILLIMETERS		HES	NOTES
STNDUL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

(5) Datum A and B to be determined at datum plane H

(6) Controlling dimension: inches

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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